

AMENDMENT

In the Specification

Please rewrite the following paragraphs as shown:

On page 1, lines 28-30,

(Amended) (W) an organoindium compound solution is applied to the open defect and then is heated to transform the applied film of the organoindium compound into a conductive layer (Japanese Unexamined Patent Application No. 3-85523),

On page 2, lines 3-6,

(Amended) (Y) an adhesive comprising fine plastic particles is applied to an open defect of a bump (Japanese Patent Application Laid-open No. 2-301723),

(Z) a conductive material is applied to an open defect and then laser irradiation is applied thereto (Japanese Patent Application Laid-Open No. 2-301723).

On page 6, lines 16-19,

(Amended) FIG. 1A, FIG. 1B and FIG. 1C schematically show steps of a method for repairing a broken defect, Fig. 1A shows a state in which paste 1 comprising metallic organic compound is applied on an open defect 6, FIG. 1B shows a state of heating the paste 1, and FIG. 1C shows the repaired state of the open defect 6 after heating.

On page 6, lines 20-28,

94 (Amended) In FIG. 1A, a substrate 10 shows a state of the substrate before repairing, in which paste 1 comprising metallic organic compound and an electrode 3 are laminated on a glass substrate 2. Glass substrate 2 is an ordinary substrate, and electrode 3 is made of ordinary material of ITO, or the like, and is formed in a line by patterning and etching on glass substrate 2 in an equal width and in an equal pitch. Further, paste 1 comprising metallic organic compound is formed by a transfer unit 4 on an open defect 6 of electrode 3 on the glass substrate 2. Open defect 6 is made in electrode 3 by a foreign substance mixed in the film plane of ITO or the like when electrode 3 is formed using an etching process (see FIG. 9C).

On page 10, lines 21-26,

95 (Amended) During the manufacture of mask 20, a metallic pattern is formed on glass substrate 21 to create an opaque film 22. Sometimes during the manufacturing process, a defect 24, shown in FIG. 8, might be accidentally formed on opaque film 22. To repair defect 24, paste 23 is transferred to defect 24 and is baked to repair defect 24. In this case, same metallic organic compound described above, to be more specific, gold paste of gold-resinate-based MOD (metalloorganic deposition) type can be used as paste 23.

On page 11, lines 1-7,

(Amended) The defect repaired in the manner described above sometimes has a portion protruding from the metallic pattern of opaque film 22 (the diagonally shaded area in FIG. 8) and the portion protruding from the metallic pattern is required to be removed because the quality of mask 20 is deteriorated in this state (in the case of the electrode, the part sticking out from the metallic pattern is acceptable, if the part is not short-circuited). To remove the protruding portion, a device for applying laser irradiation such as YAG laser is used.